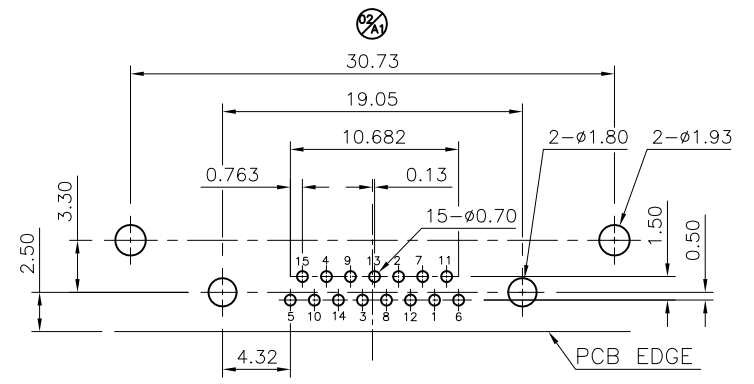
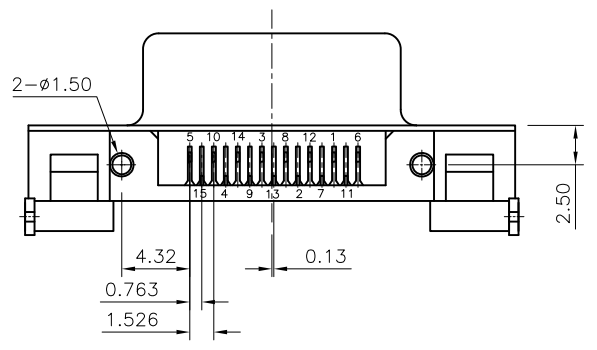
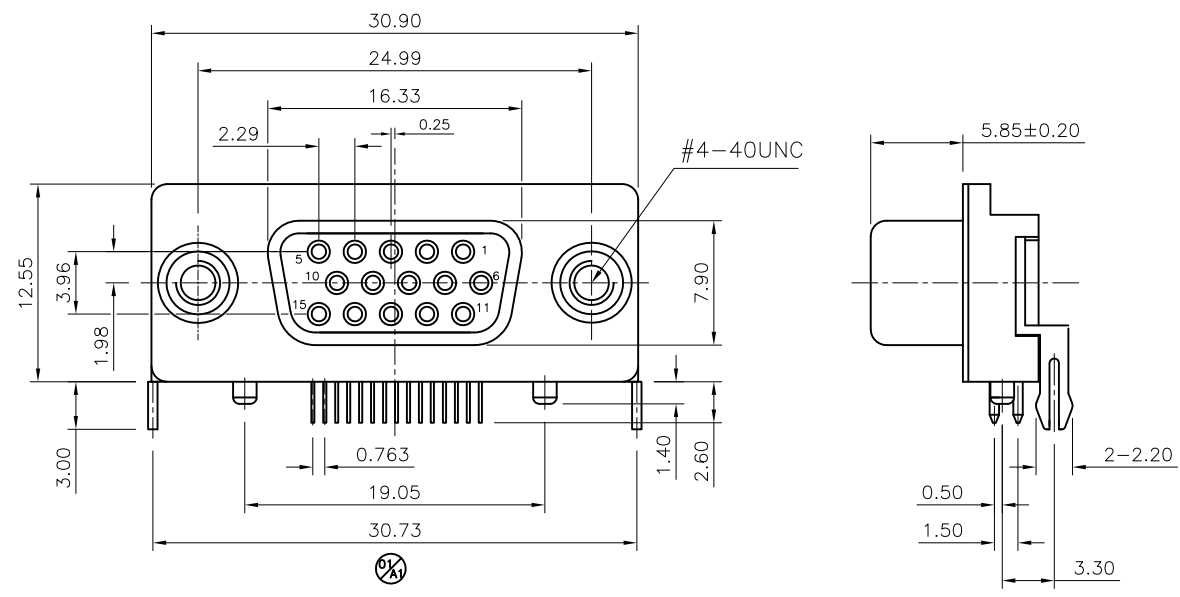


NOTES:

1. MATERIAL:
 - 1.1 INSULATOR: PA66, UL94V-0, COLOR: BLUE(300U)
 - 1.2 CONTACTS: BRASS,
 - 1.3 SHIELD: SPCC,
 - 1.4 BOARD LOCK: SPCC,
 - 1.5 RIVET: BRASS,
2. FINISH:
 - 2.1 CONTACTS: GOLD(SEE TALBE) PLATED ON CONTACT AREA, 80μ" MIN. TIN PLATED ON SOLDER AREA, 30μ" MIN. NICKEL UNDERPLATED OVERALL.
 - 2.2 SHIELD: 50μ" MIN. NICKEL PLATED ENTIRE.
 - 2.3 BOARDLOCK: 80μ" MIN. TIN PLATED ENTIRE, 30μ" MIN. NICKEL UNDERPLATED OVERALL.
 - 2.4 RIVET: 30μ" MIN. NICKEL PLATED ENTIRE.
3. SPECIFICATIONS:
 - 3.1 CURRENT RATING: 1.0A.
 - 3.2 CONTACT RESISTANCE: 25mΩ MAX.
 - 3.3 INSULATION RESISTANCE: 1000MΩ MIN.
 - 3.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 500V/ MINUTE.
 - 3.5 OPERATING TEMPERATURE: -20°C TO +85°C.
4. OTHERS:
 - 4.1 THIS COMPONENT AND ITS HOMOGENEOUS SUB COMPONENTS ARE RoHS COMPLIANT.
 - 4.2 RESISTANCE TO SOLDERING HEAT 265°C FOR 5 SECONDS.



RECOMMENDED P.C.B LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

TRAY	G/F	ACNDB210034-001
PACKING	PLATING	CPC P/N.

REV.	DESCRIPTION	ECN NO.	NAME	DATE	DIM.	TOL.
A1	MODIFY DIMENISON	N1511002	Rock	10-Nov-2015	X.	± -
A0	FIRST RELEASED	-	Rock	19-Aug-2015	X.X	± 0.30
					X.XX	± 0.25
					X.XXX	± 0.15
					ANGL	± 3°

REVISIONS

TITLE: D-SUB 15P R/A DIP REC TYPE H12.55mm			
DWG. NO.: = ACNDB210034			
UNIT: mm	DWG SIZE: A4	SCALE: none	SHEET: 1 OF 1

DRAWN: Rock	
CHECKED: Vic	
APPROVED: Kim	
RFQ NO.: Q1411061	